

RADIO FREQUENCY GROUNDING ROD
ABSTRACT OF THE DISCLOSURE

A radio frequency (RF) grounding rod employed in a plasma chamber of semiconductor equipment is disclosed. The RF grounding rod comprises a contact head and a main rod. The contact head is electrically
5 connected to an RF mesh of the plasma chamber. The main rod is coated with a conductive layer of gold, silver, nickel, aluminum or copper; one end is connected to the contact head and the other end is electrically connected to a grounding base of the plasma chamber to form an electrical
10 conductive path. The main rod is constituted of an upper rod, a lower rod and connection means therebetween. The connection means can be formed by soldering gold, silver, nickel, aluminum, copper or the alloy thereof, or by an engagement of a screw portion and a nut portion.

(FIG. 3)